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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/525,105	03/14/2000	Donald C. Abbott	TI-28098	9089
75	90 02/25/2004		EXAM	INER
Gary C Honey	cutt		WILLIAMS, AI	LEXANDER O
Texas Instrumer	nts Incorporated			
PO Box 655474	-		ART UNIT	PAPER NUMBER
MS 3999			2826	
Dallas, TX 75265			DATE MAILED: 02/25/200-	4

Please find below and/or attached an Office communication concerning this application or proceeding.

		<b>A</b> ~~
	Application No.	Applicant(s)
	09/525,105	ABBOTT ET AL.
Office Action Summary	Examiner	Art Unit
	Alexander O Williams	2826
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the	correspond nce address
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply If NO period for reply is specified above, the maximum statutory period w  - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be to within the statutory minimum of thirty (30) da will apply and will expire SIX (6) MONTHS fror cause the application to become ABANDON	mely filed ys will be considered timely. n the mailing date of this communication. ED (35 U.S.C. § 133).
Status		
<ul> <li>1) Responsive to communication(s) filed on 03 Dec</li> <li>2a) This action is FINAL. 2b) This</li> <li>3) Since this application is in condition for alloware closed in accordance with the practice under E</li> </ul>	action is non-final. nce except for formal matters, pr	
Disposition of Claims		
4) ☐ Claim(s) 1-13 and 23-26 is/are pending in the a 4a) Of the above claim(s) is/are withdray 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-13 and 23-26 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or	vn from consideration.	
Application Papers		
9) The specification is objected to by the Examine 10) The drawing(s) filed on is/are: a) access applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Examine	epted or b) objected to by the drawing(s) be held in abeyance. So ion is required if the drawing(s) is o	ee 37 CFR 1.85(a). bjected to. See 37 CFR 1.121(d).
Priority under 35 U.S.C. § 119		
a) All b) Some * c) None of:  1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the priority documents application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received in Applica ity documents have been receiv I (PCT Rule 17.2(a)).	tion No red in this National Stage
Attachment(s)	_	
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal 6) Other:	

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Serial Number: 09/525105 Attorney's Docket #: TI-28098 Filing Date: 3/14/00; claimed foreign priority to 3/19/99

Applicant: Abbott et al.

Examiner: Alexander Williams

Applicant's Appeal Brief in Paper # 22, filed 12/2/03, has been acknowledged.

Applicant's request for reconsideration of the finality of the rejection of the last Office action is persuasive and, therefore, the finality of that action is withdrawn.

Claims 14 to 22 have been canceled.

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CAR 1.56 to

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point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103© and potential 35 U.S.C. 102(f) or (g) prior art under 35 U.S.C. 103(a).

Claim 1 is rejected under 35 U.S.C. § 103(a) as being unpatentable over Hashizume (U.S. Patent # 5,946,556) in view of Huang et al. (U.S. Patent # 5,994,767).

For example, in claim 1, Hashizume (Figures 3 to 5F) specifically figure 4 show a leadframe 4 for use with packaged 1 integrated circuit chips 5 comprising: gold plated on segments of said leadframe intended for solder attachment. (see column 10, lines 26-34,(iii)). Hashizume fail to explicitly show the gold selectively plated on segments of said leadframe intended for solder attachment.

Huang et al. is cited for showing a leadframe for a integrated circuit package. Specifically, Huang et al. (figures 1 to 7) specifically figure discloses the base structure is divided into one external—lead area and one package area in including one bonding area having one die pad therein. There are various ways to form a copper layer, a nickel plating, a silver layer, a palladium/nickel (Pd/Ni) plating, a palladium (Pd) plating, and a gold layer on the leadframe, either over the entire leadframe or selectively only over specific portions of the leadframe (see column 2, lines 37) for the purpose of making solder connections.

Therefore, it would be obvious to one of ordinary skill in the art at the time of the invention to use Huang et al.'s selective plating to modify Hashizume's plating of the entire surface for the purpose of making better solder connections.

Initially, and with respect to claims 2, 11 and 13, note that a "product by process" claim is directed to the product per se, no matter how actually made, <u>In re Hirao</u>, 190 USPQ 15 at 17 (footnote 3). See also <u>In re Brown</u>, 173 USPQ 685; <u>In re Luck</u>,

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177 USPQ 523; In re Wertheim, 191 USPQ 90 (209 USPQ 554 does not deal with this issue); In re Fitzgerald, 205 USPQ 594, 596 (CCPA); In re Marosi et al., 218 USPQ 289 (CAFC); and most recently, In re Thorpe et al., 227 USPQ 964 (CAFC, 1985) all of which make it clear that it is the final product per se which must be determined in a "product by process" claim, and not the patentability of the process, and that, as here, an old or obvious product produced by a new method is not patentable as a product, whether claimed in "product by process" claims or not. Note that Applicant has burden of proof in such cases as the above case law makes clear.

Claims 2 to 13, 15 and 23 to 26 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Akino et al. (Japan Patent Application # 2000-77593) in view of Huang et al. (U.S. Patent # 5,994,767).

Akino et al. is cited for showing a lead frame for semiconductor. Specifically, Akino et al. (figures 1 to 3) specifically figure 3 discloses a leadframe 1 base made of copper 5; a first layer of nickel 6 deposited on said copper; a palladium 7 on first nickel layer; a second nickel layer 9; a layer of palladium 7; and a layer of gold 8. Akino et al. fails to explicitly show gold selectively plated on segments of said leadframe intended for solder attachment.

Huang et al. is cited for showing a leadframe for a integrated circuit package. Specifically, Huang et al. (figures 1 to 7) specifically figure discloses the base structure is divided into one external—lead area and one package area in including one bonding area having one die pad therein. There are various ways to form a copper layer, a nickel plating, a silver layer, a palladium/nickel (Pd/Ni) plating, a palladium (Pd) plating, and a gold layer on the leadframe, either over the entire leadframe or selectively only over specific portions of the leadframe (see column 2, lines 37) for the purpose of making solder connections.

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In claim 3 to 8 and 24 to 26, Note that the specification contains no disclosure of either the critical nature of the claimed dimensions or any unexpected results arising therefrom. Where patentability is said to be based upon particular chosen dimensions or upon another variable recited in a claim, the Applicant must show that the chosen dimensions are critical. In re Woodruff, 919 F.2d 1575, 1578, 16 USPQ2d 1934, 1936 (Fed. Cir. 1990).

As to claims 9 to 15, Akino et al. and Huang et al. it would be obvious to one of ordinary skill in the art to use claimed detailed on the structure of the leadframe in the device.

Therefore, it would be obvious to one of ordinary skill in the art at the time of the invention to use Huang et al.'s selective plating to modify Akino et al.'s plating of the entire surface for the purpose of making better solder connections.

As to the grounds of rejection under section 103, see MPEP \$ 2113.

## Response

Applicant's arguments filed 12/2/03 have been fully considered, but are moot in view of the new grounds of rejections detailed above. In the examination of the claims the Examiner is interested in finding the final structure of the claim language.

Field of Search	Date
U.S. Class and subclass: 257/666,675-678,690,692,693,696,698, 712,713,762,741,766-768,772,779,784,788	3/23/01 4/14/02 6/25/02 .12/15/02 6/13/03 2/23/04
Other Documentation: foreign patents and literature in 257/666,675-678,690,692,693,696,698, 712,713,762,741,766-768,772,779,784,788	3/23/01 4/14/02 6/25/02 12/15/02

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	6/13/03 2/23/04
Electronic data base(s): U.S. Patents EAST	3/23/01 4/14/02 6/25/02 12/15/02 6/13/03 2/23/04

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Alexander O Williams whose telephone number is (571) 272 1924. The examiner can normally be reached on M-F 6:30-7:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (571) 272 1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

AOW 2/23/04

Alexander Williams
Primary Examiner